L	Hits	Search Text	DB	Time stamp
Number				
1	1573	(250/281,282).CCLS.	USPAT;	2003/11/25
			US-PGPUB	10:49
2	783	(438/745).CCLS.	USPAT;	2003/11/25
			US-PGPUB	10:49
3	884	(436/43,47).CCLS.	USPAT;	2003/11/25
			US-PGPUB	10:49
4	3944	(134/2,10,22.14,32,48,71,79,80).CCLS.	USPAT;	2003/11/25
			US-PGPUB	10:50
5	7145	((250/281,282).CCLS.) or	USPAT;	2003/11/25
		((438/745).CCLS.) or ((436/43,47).CCLS.)	US-PGPUB	10:51
		or		
		((134/2,10,22.14,32,48,71,79,80).CCLS.)		
6	1	(((250/281,282).CCLS.) or	USPAT;	2003/11/25
		((438/745).CCLS.) or ((436/43,47).CCLS.)	US-PGPUB	10:53
		or		
		((134/2,10,22.14,32,48,71,79,80).CCLS.))		
		and ((wafer near4 contaminat\$5 near4		
		edge) with solvent)		
7	4	· · · · · · · · · · · · · · · · · · ·	USPAT;	2003/11/25
		((438/745).CCLS.) or ((436/43,47).CCLS.)	US-PGPUB	10:53
		or		
		((134/2,10,22.14,32,48,71,79,80).CCLS.))		
		and ((wafer near4 contaminat\$5) with		
		solvent)		

	σ	1	Docum nt	ID	Issue Date	Pages	Title	Current OR
1			US 200301088 A1	823	20030612		Method and apparatus for removing organic films	430/329
2			US 200300174 A1	419	20030123	40	Mass production method of semiconductor integrated circuit device and manufacturing method of electronic device	430/311
3			US 200201534 A1	482	20021024		Method and apparatus for detecting contaminating species on a wafer edge	250/281
4			US 549829 A	93	19960312		Cleaning wafer substrates of metal contamination while maintaining wafer smoothness	134/3

	Current XRef	Retrieval Classif	Inventor	s	С	P	2	3	4	5
1	134/10; 134/109; 134/11; 134/122P; 134/38; 134/64P; 510/176		Muraoka, Hisashi et al.	×						
2	257/E21.30 9; 430/330; 438/689; 438/745; 438/754; 438/758		Futase, Takuya et al.	⊠						
3			Lin, Ying-Chuan	×						
4	134/2; 257/E21.22 8		Ilardi, Joseph M. et al.	⊠						

	I	PT	
1	US	20030108823	
2	US	20030017419	
3	US	20020153482	
4	US	5498293	